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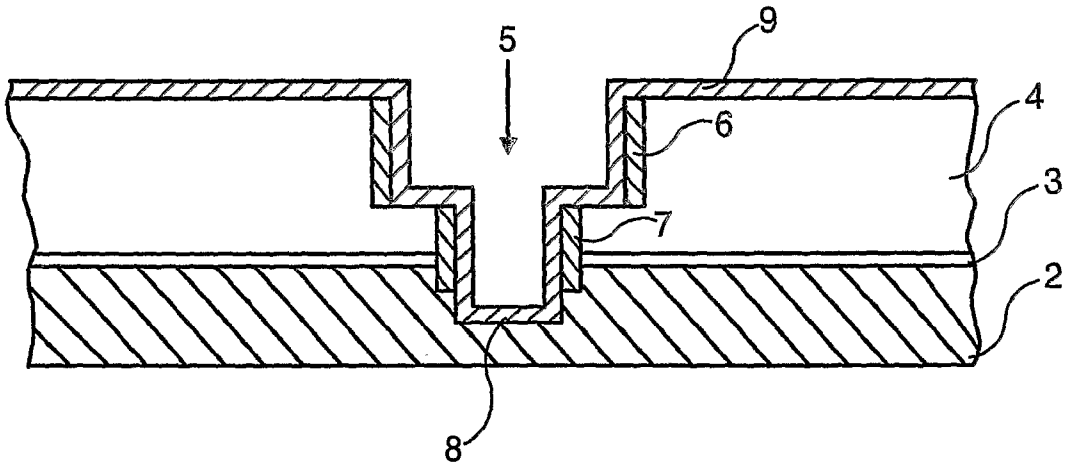
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(54) Title: SACRIFICIAL METAL LINER FOR COPPER INTERCONNECTS



(57) Abstract: A semiconductor device which includes an improved liner structure formed in a via (5) having extended sidewall portions and a bottom (8) penetrating a metal liner (7). The liner structure includes two liner layers, the first (6) being on the via sidewalls, but not the bottom, and the second being (9) on the first layer and the extended sidewall portions and bottom of the via. A method of making the liner structure, in which the first layer is deposited prior to an etching or cleaning step, which extends the via into the metal line, is also disclosed.

WO 2004/070830 A1

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